Plastic Packages for Integrated Circuits

Package Outline Drawing

W5x6.30A
5X6 ARRAY 30 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP) BSC
Rev 0, 6/13

2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. There shall be a minimum clearance of 0.10mm between the edge of the bump and the body edge.